Product / Package Information

Package	SOIC_IC
Body Size	300 mils
Lead Count	16
Terminal Finish	100Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	No
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.20 E-01	86.20	862000	59.16	591589
Thermosets	Epoxy resin	Proprietary	2.78 E-02	7.50	75000	5.15	51472
Thermosets	Phenol Novolac	9003-35-4	1.48 E-02	4.00	40000	2.75	27452
Other inorganic materials	Antimony Trioxide	1309-64-4	5.57 E-03	1.50	15000	1.03	10294
Thermosets	Brominated Resin	40039-93-8	1.86 E-03	0.50	5000	0.34	3431
Other inorganic materials	Carbon Black	1333-86-4	1.11 E-03	0.30	3000	0.21	2059
Subtotal			3.71 E-01	100	1000000	68.63	686299

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.45 E-01	97.57	975706	26.84	268388
Copper & its alloys	Iron	7439-89-6	3.39 E-03	2.28	22789	0.63	6269
Copper & its alloys	Zinc	7440-66-6	1.88 E-04	0.13	1263	0.03	347
Copper & its alloys	Phosphorus	7723-14-0	3.60 E-05	0.02	242	0.01	67
Subtotal			1.49 E-01	100.00	1000000	27.51	275071

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.50 E-03	100.0	1000000	0.28	2778

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.53 E-03	100.0	1000000	1.02	10232

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold		1.20 E-03	99.99	1000000	0.22	2220

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon		1.03 E-02	100.0	1000000	1.91	19053

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.88 E-03	80	800000	0.35	3478
Thermosets	Epoxy Resin	Proprietary	3.53 E-04	15	150000	0.07	652
Others	Curing agent & hardener	Proprietary	1.18 E-04	5	50000	0.02	217
Subtotal			2.35 E-03	100	1000000	0.43	4347

	Weight (g)		Percentage (%)	PPM
Package Totals	**5.41 E-01**		**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES